

RoHS Compliant Product

A suffix of "-C" specifies halogen & lead-free

## DESCRIPTION

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $R_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

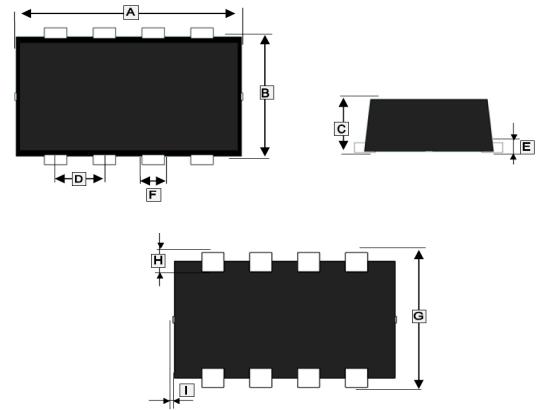
## FEATURES

- Low  $R_{DS(on)}$  provides higher efficiency and extends battery life.
- Low thermal impedance copper leadframe DFN2\*3 saves board space.
- Fast switching speed.
- High performance trench technology.

## PACKAGE INFORMATION

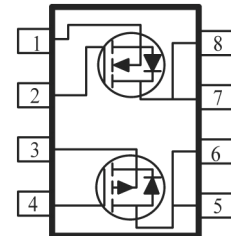
Package	MPQ	Leader Size
DFN2*3	3K	13' inch

**DFN2\*3**



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	3.00 BSC.		F	0.24	0.35
B	1.70 BSC.		G	2.00 BSC.	
C	0.70	0.90	H	0.20	0.40
D	0.65 BSC.		I	0	0.15
E	0.08	0.25			

**Top View**



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating		Unit	
		N-CH	P-CH		
Drain-Source Voltage	$V_{DS}$	20	-20	V	
Gate-Source Voltage	$V_{GS}$	$\pm 8$	$\pm 8$	V	
Continuous Drain Current <sup>1</sup>	$I_D$	$T_A = 25^\circ\text{C}$	5	-4.7	A
		$T_A = 70^\circ\text{C}$	4.1	-3.9	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	8	-8	A	
Continuous Source Current (Diode Conduction) <sup>1</sup>	$I_S$	4.5	-4.5	A	
Total Power Dissipation <sup>1</sup>	$P_D$	$T_A = 25^\circ\text{C}$	2.1		W
		$T_A = 70^\circ\text{C}$	1.3		W
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 ~ 150		$^\circ\text{C}$	
<b>Thermal Resistance Ratings</b>					
Maximum Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	$t \leq 10$ sec	62.5		$^\circ\text{C} / \text{W}$
		Steady State	80		$^\circ\text{C} / \text{W}$

Notes:

- 1 Surface Mounted on 1" x 1" FR4 Board.
- 2 Pulse width limited by maximum junction temperature.

**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Ch	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>							
Gate Threshold Voltage	V <sub>GS(th)</sub>	N	1	-	-	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
		P	-1	-	-		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA
Gate-Body Leakage	I <sub>GSS</sub>	N	-	-	100	μA	V <sub>DS</sub> =0, V <sub>GS</sub> =8V
		P	-	-	-100		V <sub>DS</sub> =0, V <sub>GS</sub> = -8V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	N	-	-	1	μA	V <sub>DS</sub> =16V, V <sub>GS</sub> =0
		P	-	-	-1		V <sub>DS</sub> = -16V, V <sub>GS</sub> =0
		N	-	-	10		V <sub>DS</sub> =16V, V <sub>GS</sub> =0, T <sub>J</sub> =55°C
		P	-	-	-10		V <sub>DS</sub> = -16V, V <sub>GS</sub> =0, T <sub>J</sub> =55°C
On-State Drain Current <sup>1</sup>	I <sub>D(on)</sub>	N	5	-	-	A	V <sub>DS</sub> =5V, V <sub>GS</sub> =4.5V
		P	-5	-	-		V <sub>DS</sub> = -5V, V <sub>GS</sub> = -4.5V
Drain-Source On-Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	N	-	-	58	mΩ	V <sub>GS</sub> =4.5V, I <sub>D</sub> =1A
			-	-	64		V <sub>GS</sub> =2.5V, I <sub>D</sub> =1A
		P	-	-	77		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -1A
			-	-	85		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -1A
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	N	-	10	-	S	V <sub>DS</sub> =5V, I <sub>D</sub> =1A
		P	-	5	-		V <sub>DS</sub> = -5V, I <sub>D</sub> = -1A
Diode Forward Voltage <sup>1</sup>	V <sub>SD</sub>	N	-	0.8	-	V	V <sub>GS</sub> =0, I <sub>S</sub> =1A
		P	-	-0.83	-		V <sub>GS</sub> =0, I <sub>S</sub> = -1A
<b>Dynamic <sup>2</sup></b>							
Total Gate Charge	Q <sub>g</sub>	N	-	2	-	nC	N-Channel I <sub>D</sub> =1A, V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V  P-Channel I <sub>D</sub> = -1A, V <sub>DS</sub> = -15V, V <sub>GS</sub> = -4.5V
		P	-	7	-		
Gate-Source Charge	Q <sub>gs</sub>	N	-	0.4	-		
		P	-	1	-		
Gate-Drain Charge	Q <sub>gd</sub>	N	-	0.7	-		
		P	-	2	-		
Turn-On Delay Time	T <sub>d(on)</sub>	N	-	6	-	nS	N-Channel V <sub>DD</sub> =15V, V <sub>GEN</sub> =4.5V I <sub>D</sub> =1A, R <sub>GEN</sub> =15Ω  P-Channel V <sub>DD</sub> = -15V, V <sub>GEN</sub> = -4.5V I <sub>D</sub> =1A, R <sub>GEN</sub> =15Ω
		P	-	10	-		
Rise Time	T <sub>r</sub>	N	-	9	-		
		P	-	1	-		
Turn-Off Delay Time	T <sub>d(off)</sub>	N	-	5	-		
		P	-	11	-		
Fall Time	T <sub>f</sub>	N	-	16	-		
		P	-	12	-		

Notes:

1. Pulse test : PW ≤ 300μs duty cycle ≤ 2%.
2. Guaranteed by design, not subject to production testing.